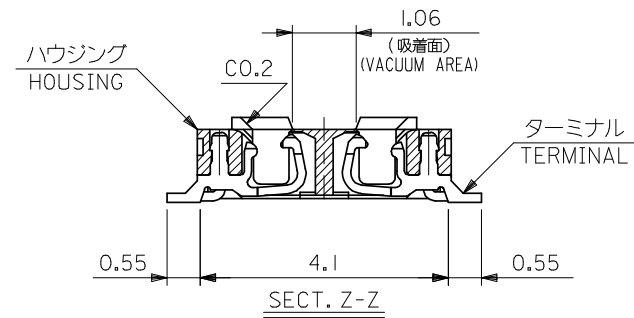
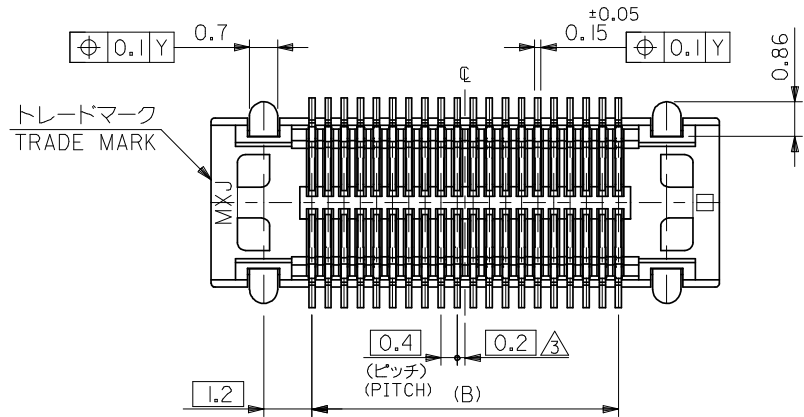
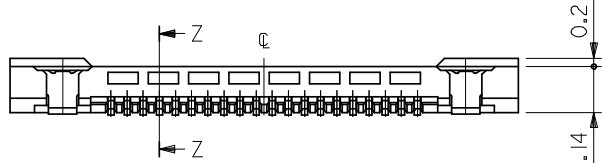
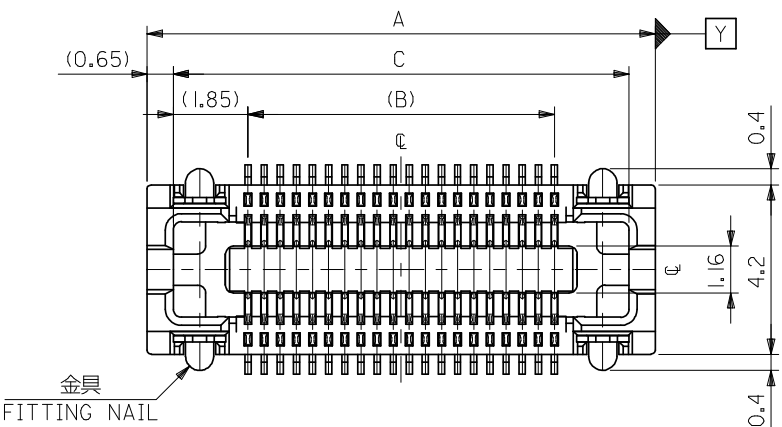


19.3	15.6	20.6	54765-8070	54765-8009	80
17.3	13.6	18.6	-7070	-7009	70
14.1	10.4	15.4	-5470	-5409	54
13.3	9.6	14.6	-5070	-5009	50
12.5	8.8	13.8	-4670	-4609	46
12.1	8.4	13.4	-4470	-4409	44
11.3	7.6	12.6	-4070	-4009	40
9.3	5.6	10.6	-3070	-3009	30
8.1	4.4	9.4	-2470	-2409	24
7.7	4.0	9.0	54765-2270	54765-2209	22
C	B	A	EMBOSSD TAPE PKG. ORDER No. オーダー番号	MATERIAL NO.	CIRCUIT

REVISED
EC NO: J2009-0301
DRWN: MABEI
CHKD: THARUYAMA
APPR: NUKITA
A

DESCRIPTION
2008/08/27
2008/08/28
2008/08/28

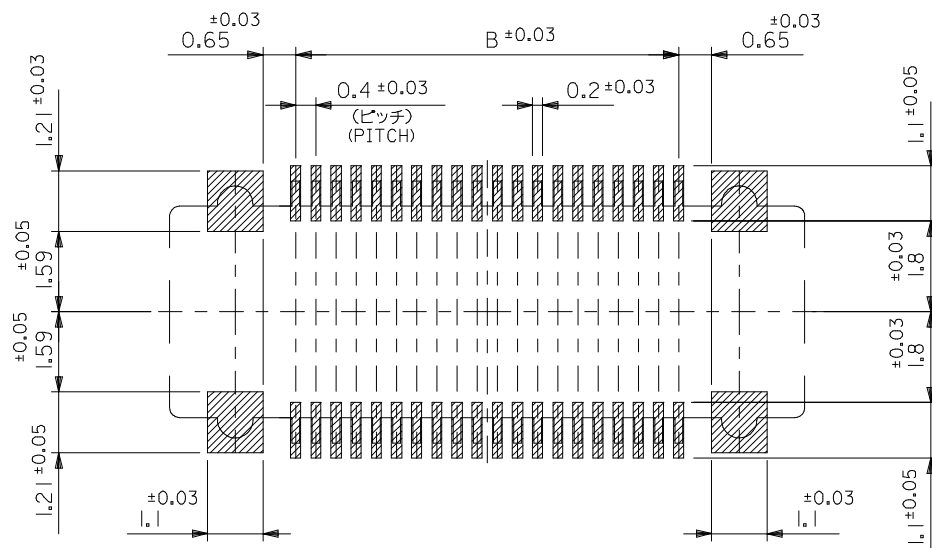
GENERAL TOLERANCES
(UNLESS SPECIFIED)
10 UNDER ±0.2
10 OVER 30 UNDER ±0.25
30 OVER ±0.3
ANGULAR ±3 °
DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY
DRAWN BY
M. NINOMIYA
DATE
'04/02/19
CHECKED BY
K. TOJO
DATE
'04/02/19
APPROVED BY
M. SASAO
DATE
'04/02/19
MATERIAL NO.
SEE TABLE
SIZE
A3

SCALE

TITLE
0.4 B-TO-B REC HSG ASSY
WITH GUIDE HGT=1.5 NI
-LEAD FREE-
MOLEX INCORPORATED
SD-54765-030
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MODEL NO.
54765-***9
DESIGN UNITS
METRIC
THIRD ANGLE
PROJECTION
DOCUMENT NO.
SHEET NO.
1 OF 2



参考基板レイアウト（マウント面）

P.C.BOARD PATTERN DIMENSION.(REFERENCE)
(MOUNTING AREA)

注記 NOTES

I. 使用材料 MATERIAL

- ハウジング：液晶ポリマー ガラス充填 UL94V-0 (黒)
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED)
UL94V-0 (COLOR: BLACK)
ターミナル：リン青銅 (t=0.15)
TERMINAL: PHOSPHOR BRONZE (t=0.15)
金具：リン青銅 (t=0.15)
FITTING NAIL: PHOSPHOR BRONZE (t=0.15)

△2 メッキ仕様 PLATING

- ターミナル TERMINAL
金メッキ 0.25マイクロメートル以上（コンタクト部）
GOLD 0.25MICROMETER MINIMUM (CONTACT AREA)
金メッキ 0.4マイクロメートル以下（テール部）
GOLD 0.4MICROMETER MAXIMUM (TAIL AREA)
下地メッキ：ニッケルメッキ 1.5マイクロメートル以上
UNDER PLATING: NICKEL 1.5MICROMETER MINIMUM
*コンタクト部とテール部はニッケルメッキによって分断されている金メッキです。
DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT PART
AND THE TAIL PART BY THE NICKEL PLATING.

金具 FITTING NAIL

- 錫メッキ 1マイクロメートル以上
Sn 1 MICROMETER MINIMUM
下地メッキ: ニッケルメッキ 1マイクロメートル以上
UNDER PLATING: NICKEL 1 MICROMETER MINIMUM

△3 (全極数/2) = 偶数の場合に適用。
APPLY FOR (CIRCUIT/2)=EVEN

4. 嵌合相手： 55604 シリーズ。
MATE WITH : 55604 SERIES.
5. テール平坦度は、0.08以下
テール及び金具の平坦度は、0.1以下
TAIL COPLANARITY TO BE 0.08MAXIMUM.
TAIL AND FITTING NAIL
COPLANARITY TO BE 0.1 MAXIMUM.
6. 本製品は 54765-***3 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54765-***3.

REVISED EC NO: J2009-0301 DRAWN:WABEI CHKD:THIRUJANA APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY M. NINOMIYA	DATE '04/02/19	TITLE 0.4 B-TO-B REC HSG ASSY WITH GUIDE HGT=1.5 NI -LEAD FREE-				
		10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '04/02/19					
		30 OVER	± ---	APPROVED BY M. SASAO	DATE '04/02/19	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-54765-030		2 OF 2		
	REV	A	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

DWG. NO.
SD-54765-031

F

D

V

C

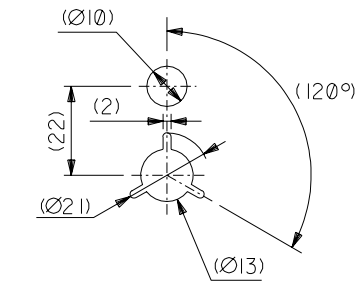
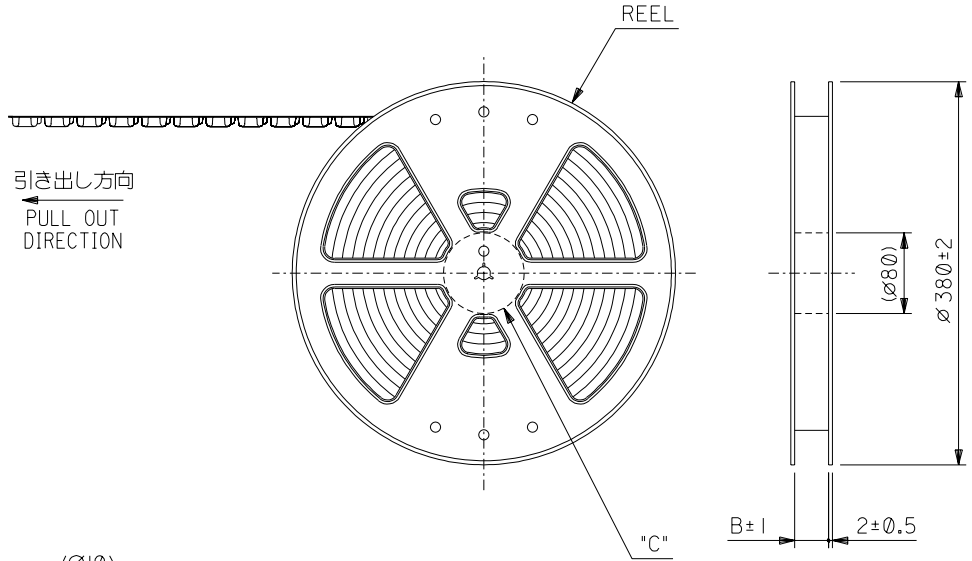
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DO NOT SCALE DRAWING

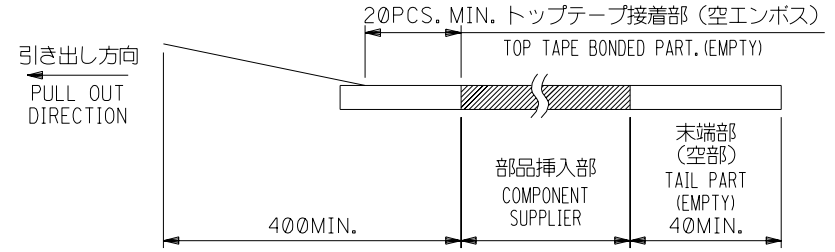
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注記 NOTES

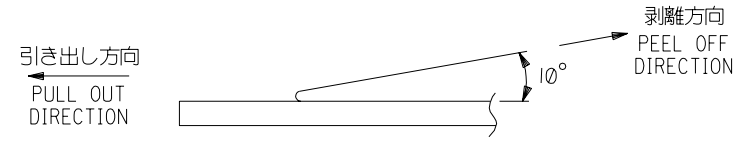
- 製品詳細寸法については図面 SD-54765-026 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54765-026
- 梱包数量：2500個/リール
NUMBER OF CONNECTORS : 2500PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



DETAIL "C"



- トップテープの剥離強度：0.1N ～ 1.3N(10gf ～ 130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ～ 1.3N(10gf ～ 130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE)：ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE)：PET , PE , PEF
リール (REEL)：ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 54765-***4 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54765-***4.

EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		RELEASED '04/02/19 EC NO. J2004-2532 DRWN: M.NINOMIYA CHK: K.TOJO APPR: M.SASAO		DESCRIPTION		MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE --		DESIGN UNITS ☒ mm ☐ INCH		MODEL NO. 54765-***0		DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT REV			
										注記参照 SEE NOTES		FINISH 仕上り		10 UNDER 未満		±0.2		DRAWN BY & DATE M.NINOMIYA '04/02/19		TITLE: 0.4 B-To-B Rec Assy W/Gde (Hgt=1.5) [Ni Barrier] Embstp Pkg -LEAD FREE-		 THIRD ANGLE PROJECTION		REVISE ON CAD ONLY			
												10 OVER 以上		30 UNDER 未満		±0.25		CHECKED BY & DATE K.TOJO '04/02/19									
														30 OVER 以上		±0.3		APPROVED BY & DATE M.SASAO '04/02/19		MOLEX MOLEX INCORPORATED							
												WIRE RANGE 適用電線範囲				ANGLE 角度		±3°		CAD FILENAME SD-54765-031.S01		MATERIAL NO. SEE CHART		DRAWING NO. SD-54765-031		SHEET NO. 1 OF 3	
										REV		INS. RANGE 被覆外径				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.										SIZE B	

8 7 6 5 4 3 2 1

SD-54765-031.S01

DWG. NO.
SD-54765-031

F

D

C

B

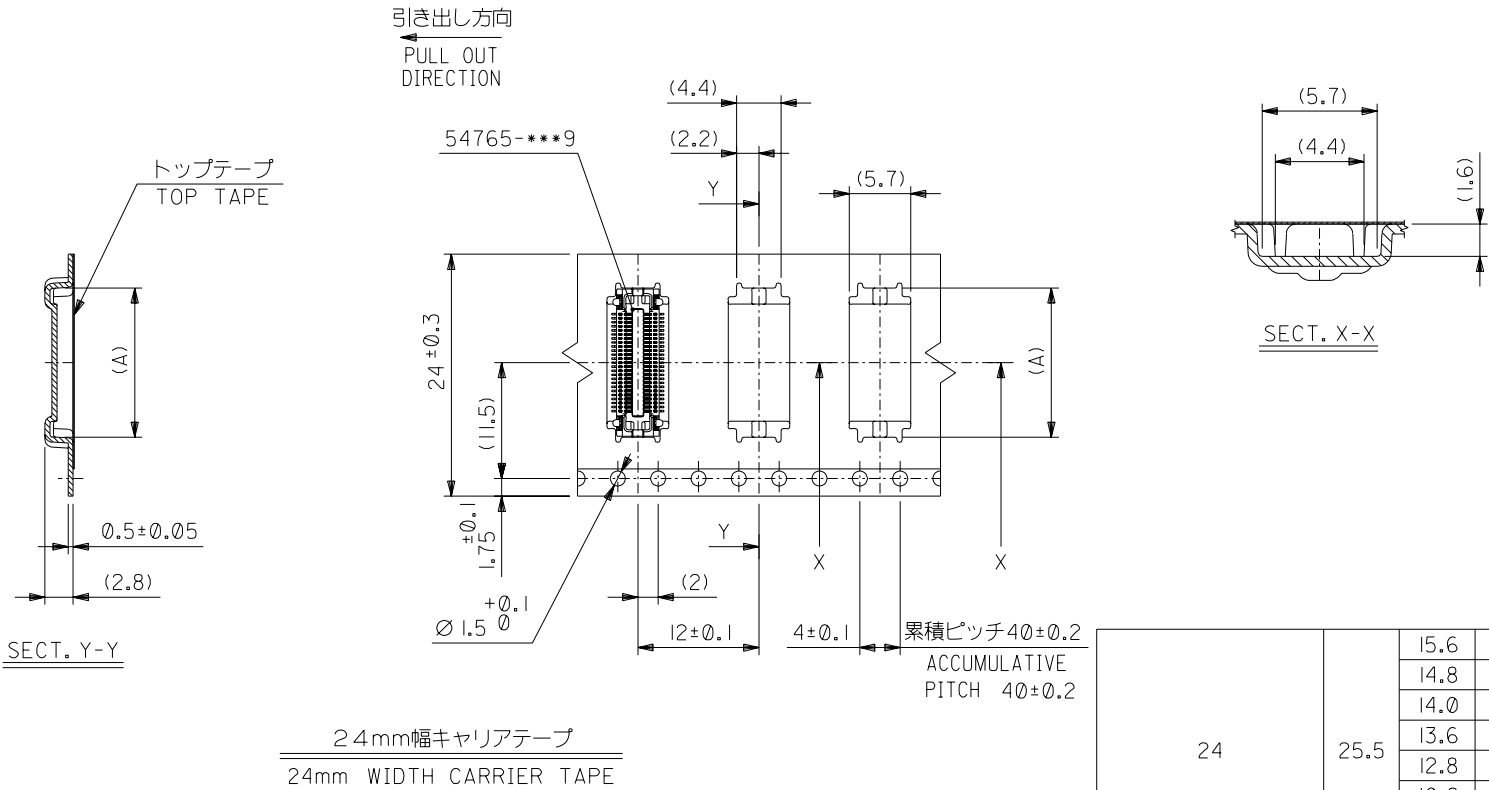
DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/02/19 EC NO. J2004-2532 DRWN: M.NINOMIYA CHK: K.TOJO APPR: M.SASAO
					0

MATERIAL 材料	注記参照 SEE NOTES
FINISH 仕上げ	//
WIRE RANGE 適用電線範囲	//
INS. RANGE 被覆外径	//

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE //	DESIGN UNITS ☒ mm ☐ INCH	DRAWN BY & DATE M.NINOMIYA '04/02/19	CHECKED BY & DATE K.TOJO '04/02/19	APPROVED BY & DATE M.SASAO '04/02/19	CAD FILENAME SD-54765-031.S02
10 UNDER 未満	±0.2					
10 OVER 30 UNDER 以上 未満	±0.25					
30 OVER 以上	±0.3					
ANGLE 角度	±3°					

MODEL NO. 54765-***0	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY	SHT 2	REV OF 3
CARRIER TAPE WIDTH 24	B	(A)	MATERIAL NO.
TITLE: 0.4 B-To-B Rec Assy W/Gde (Hgt=1.5) [Ni Barrier] Embstp Pkg -LEAD FREE-			
MOLEX INCORPORATED			
MATERIAL NO. SEE CHART		DRAWING NO. SD-54765-031	SHEET NO. 2 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			
SIZE B			



F

E

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SD-54765-031.S02

DWG. NO.
SD-54765-031

F

D

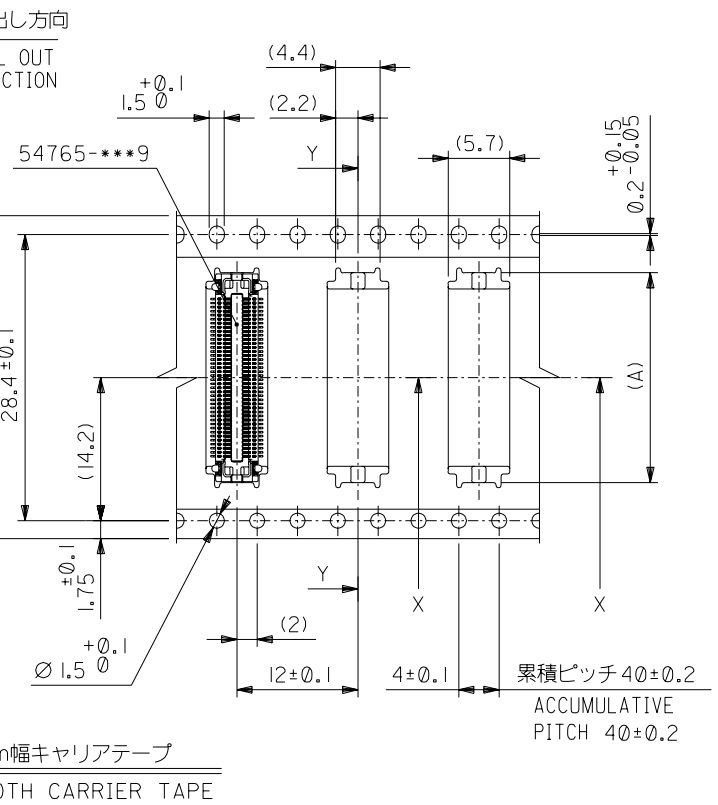
V

C

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DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/02/19 EC NO. J2004-2532 DRWN: M.NINOMIYA CHK: K.TOJO APPR: M.SASAO	DESCRIPTION	MATERIAL 材料
							注記参照 SEE NOTES
							FINISH 仕上げ
							WIRE RANGE 適用電線範囲
						REV	INS. RANGE 被覆外径



32	33.5	20.8	54765-8070	80
		18.8	54765-7070	70
キャリアテープ幅 CARRIER TAPE WIDTH	B	(A)	MATERIAL NO.	極数 CIRCUIT
MODEL NO.	54765-***0	DIMENSIONS:	SHT	REV
DESIGN UNITS	THIRD ANGLE PROJECTION	☐ mm ☐ INCH ☒ mm ONLY		
DRAWN BY & DATE M.NINOMIYA '04/02/19	TITLE: 0.4 B-To-B Rec Assy W/Gde (Hgt=1.5) [Ni Barrier] Embstp Pkg -LEAD FREE-			
CHECKED BY & DATE K.TOJO '04/02/19	MOLEX INCORPORATED			
APPROVED BY & DATE M.SASAO '04/02/19	CAD FILENAME SD-54765-031.S03	MATERIAL NO. SEE CHART	DRAWING NO. SD-54765-031	SHEET NO. 3 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B